



40V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
40V	$6m\Omega @ V_{GS} = 10V$	140A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features

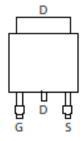
- Low On-Resistance
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMNH4006SK3Q)

Mechanical Data

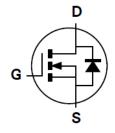
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.315 grams (Approximate)



Top View



Pin Out Top View



Equivalent Circuit

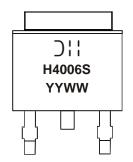
Ordering Information (Note 4)

Part Number	Case	Packaging
DMNH4006SK3-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Dil =Manufacturer's Marking
H4006S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Digit of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	40	V	
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	20 16	А
Continuous Drain Current (Note 7) $V_{GS} = 10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$		Δ	140 100	А
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)	I _{DM}	200	Α	
Maximum Continuous Body Diode Forward Current (Note 7)	Is	120	Α	
Avalanche Current, L = 0.1mH (Note 8)	I _{AS}	64	А	
Avalanche Energy, L = 0.1mH (Note 8)	E _{AS}	208	mJ	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P _D	2.2	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	<u> </u>	68	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	29	
Total Power Dissipation (Note 6)		P_{D}	3.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	Б	42	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	21	
Thermal Resistance, Junction to Case (Note 7)		$R_{ heta JC}$	0.8	
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, T _J = +25°C	I _{DSS}	_		1	μΑ	$V_{DS} = 40V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	2	_	4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	6	mΩ	$V_{GS} = 10V, I_D = 86A$	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.0A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}	_	2,280	_	рF	.,	
Output Capacitance	Coss	_	556	_	pF	$V_{DS} = 25V, V_{GS} = 0V,$ - f = 1MHz	
Reverse Transfer Capacitance	C _{rss}		282	_	pF		
Gate Resistance	R_g	_	1.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 6V)	Q_g	_	32	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	51	_	nC	V _{DS} = 32V. I _D = 86A	
Gate-Source Charge	Q_{gs}	_	9.6	_	nC	VDS = 32V, ID = 66A	
Gate-Drain Charge	Q_{gd}	_	20.4		nC		
Turn-On Delay Time	t _{D(ON)}	_	7.7	_	ns		
Turn-On Rise Time	t _R	_	9.3	_	ns	$V_{GS} = 10V, V_{DS} = 20V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	18	_	ns	$R_G = 3.5\Omega, I_D = 86A$	
Turn-Off Fall Time	t _F		8.1	_	ns]	
Body Diode Reverse Recovery Time	t _{RR}	_	32	_	ns	$I_F = 50A$, $di/dt = 100A/\mu s$	
Body Diode Reverse Recovery Charge	Q _{RR}	_	28	_	nC	$I_F = 50A$, di/dt = 100A/ μ s	

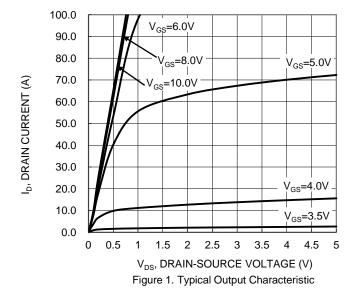
Notes:

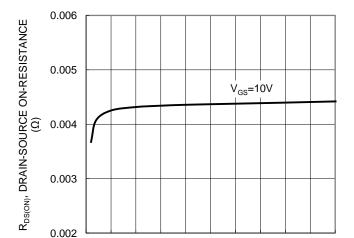
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.

- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.









 ${\rm I_D}, {\rm DRAIN\text{-}SOURCE}$ CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

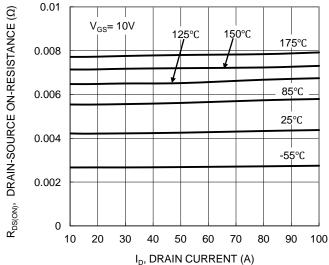
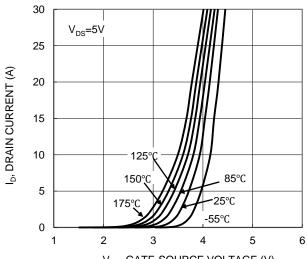
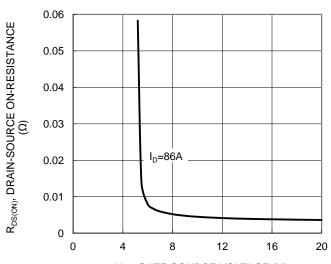


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic



V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic

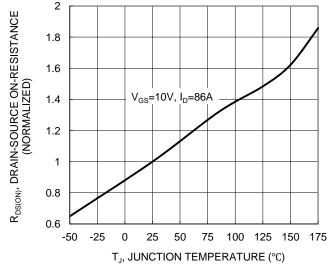


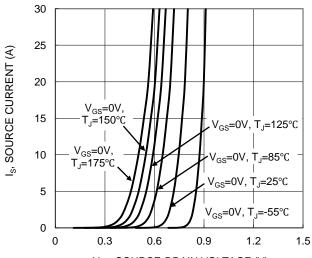
Figure 6. On-Resistance Variation with Junction
Temperature

0 5 10 15 20 25 30 35 40 45 50



O.009 O.009 V_{GS}=10V, I_D=86A O.003 O.

T_J, JUNCTION TEMPERATURE (°C) Figure 7. On-Resistance Variation with Junction Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

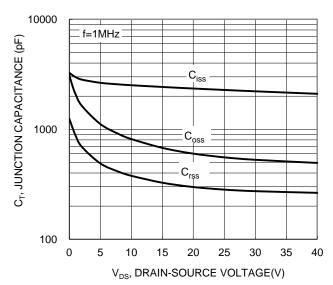


Figure 11. Typical Junction Capacitance

DMNH4006SK3

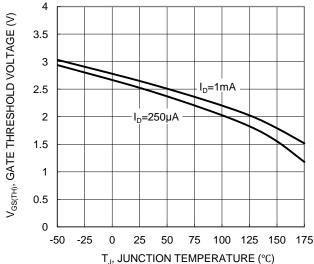


Figure 8. Gate Threshold Variation vs. Junction Temperature

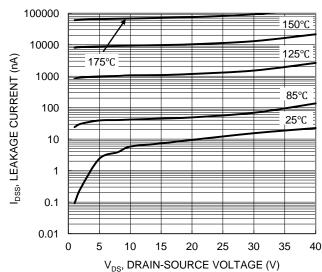


Figure 10. Typical Drain-Source Leakage Current vs.

Voltage

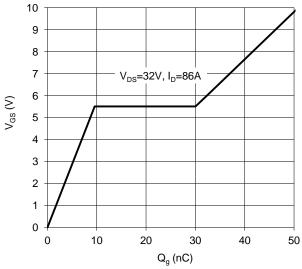


Figure 12. Gate Charge



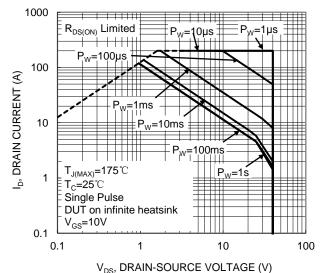


Figure 13. SOA, Safe Operation Area

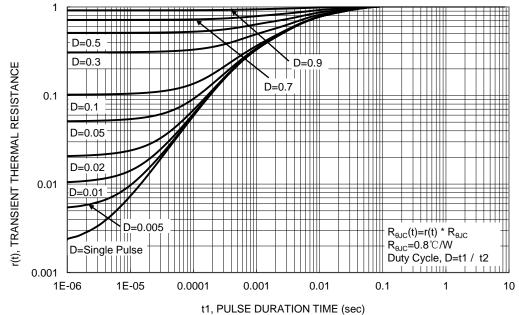
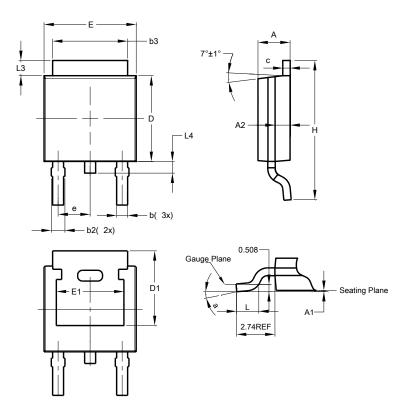


Figure 14. Transient Thermal Resistance



Package Outline Dimensions

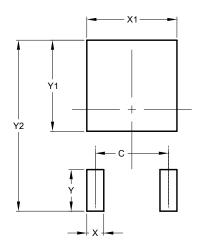
Please see http://www.diodes.com/package-outlines.html for the latest version.



TO252 (DPAK)						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A 1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
b	0.64	0.88	0.783			
b2	0.76	1.14	0.95			
b3	5.21	5.46	5.33			
С	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	-	-			
е	-	-	2.286			
П	6.45	6.70	6.58			
E1	4.32	-	-			
H	9.40	10.41	9.91			
٦	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
L4	0.64	1.02	0.83			
а	0°	10°	-			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	4.572			
Х	1.060			
X1	5.632			
Υ	2.600			
Y1	5.700			
Y2	10.700			



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